# High Frequency Winding Type Chip Inductor SWI0603F-43NG

	ECN HISTORY LIST										
REV	DATE	DESCRIPTION	APPROVED	APPROVED CHECKED							
1.0	18/05/09	新 發 行	楊祥忠	徐鋒強	張展耀						
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# **High Frequency Winding Type Chip Inductor**

SWI0603F-43NG

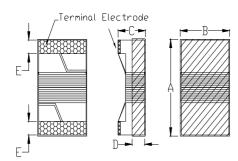
### 1. Features

- 1.Ceramic core wire wound construction.
- 2.No batch to batch variations in inductance
- 3. High Reliability due to ceramic wire wound construction.
- 4. High frequency application.
- 5.Small footprint as well as low profile.
- 6.100% Lead(Pb) & Halogen-Free and RoHS compliant.





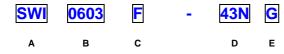
### 2. Dimensions



Size	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
SWI0603	1.80 max.	1.20 max.	1.20 max.	0.38 ref.	0.35±0.1

Unit:mm

### 3. Part Numbering



A: Series

B: Dimension LxW

C: Lead free type

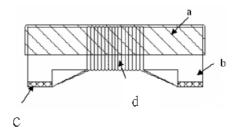
D: Inductance 43N=43.0nH E: Inductance Tolerance G=±2%

### 4. Specification

Part Number	Inductance (nH)	Tolerance	Test Frequency (Hz)	Q @ 250MHz min.	Rated Current (mA) max.	DCR $(\Omega)$ max.	SRF (MHz) min.
SWI0603F-43NG	43	G	0.1V/250M	38	600	0.28	2000

### 5. Materials

No.	Description	Specification
a.	Upper Plate	UV Glue
b.	Core	Ceramics Core
С	Termination	Tin Pb Free
d	Wire	Enameled Copper Wire



## 6. Reliability and Test Condition

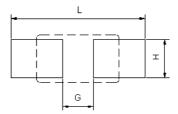
Item	Performance	Test Condition
Operating temperature	-40~+125°C (Including self - temperature rise)	
Storage temperature	-40~+125℃ (on board)	
Electrical Performance Te	est	
Inductance L		Agilent-4291, Agilent-4287
Q		Agilent-4192, Agilent-4285
SRF	Defer to standard electrical pharacteristic list	Agilent-4291 Agilent-4192
DC Resistance	Refer to standard electrical characteristic list	Agilent-34420A
Rated Current		Applied the current to coils, the inductance change shall be less than 20% to initial value.
Reliability Test		
Life Test		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles)  Temperature: 125±2°C  Applied current: rated current  Duration: 1000±12hrs  Measured at room temperature after placing for 24±2 hrs
Load Humidity		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Humidity: 85±2%R.H,  Temperature: 85°C±2°C  Duration: 1000hrs Min. with 100% rated current
Moisture Resistance	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Measured at room temperature after placing for 24±2 hrs  Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles  1. Baked at50℃ for 25hrs, measured at room temperature after placing for 4 hrs.  2. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs.  3. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs, keep at 25℃ for 2 hrs then keep at -10℃ for 3 hrs  4. Keep at 25℃ 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles Condition for 1 cycle Step1: -40±2°C 30±5min Step2: 25±2°C ≤0.5min Step3: 125±2°C 30±5min Number of cycles: 500
Vibration		Measured at room temperature after placing for 24±2 hrs Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes Equipment: Vibration checker Total Amplitude:1.52mm±10% Testing Time: 12 hours(20 minutes, 12 cycles each of 3 orientations).

Item	Performance	Test Condition				
Bending	Appearance: No damage. Impedance: within±15% of initial value	Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm Bending depth: >=0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.				
	Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Type Peak Value duration (D) Wave form Civift/sec Velocity change (Vi)ft/sec				
Shock	exceed the specification value	SMD         50         11         Half-sine         11.3           Lead         50         11         Half-sine         11.3				
Solder ability	More than 95% of the terminal electrode should be covered with solder.	Preheat: 150°C,60sec.₀ Solder: Sn96.5% Ag3% Cu0.5% Temperature: 245±5°C∘ Flux for lead free: Rosin. 9.5%∘ Dip time: 4±1sec∘ Depth: completely cover the termination				
Resistance to Soldering Heat		Depth: completely cover the termination  Temperature (°C) Time(s) Temperature ramp/immersion and emersion rate leat cycles (solder temp) 10 ±1 25mm/s ±6 mm/s 1				
Terminal Strength	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value e	Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a force(>0805:1kg, <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.				

### 7. Soldering and Mounting

#### 7-1. Recommended PC Board Pattern

Chip size						Land Patterns For Reflow Soldering			
Series	Туре	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	L(mm)	G(mm)	H(mm)
SWI	0603	1.80max.	1.20max.	1.20max	0.38 ref	0.35±0.1	1.92	0.90	1.02



PC board should be designed so that products can prevent damage from mechanical stress when warping the board. Products shall be positioned in the sideway direction to against the mechanical stress to prevent failure.

#### 7-2. Soldering

Mildly activated rosin fluxes are preferred. TAI-TECH terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

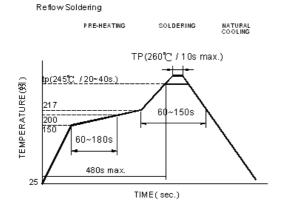
#### 7-2.1 Solder re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

#### 7-2.2 Soldering Iron(Figure 2):

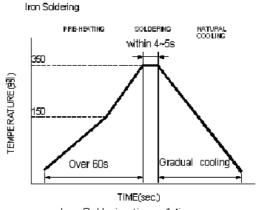
Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

- $\bullet$  Preheat circuit and products to 150  $^\circ\! {\mathbb C}$
- Never contact the ceramic with the iron tip
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- 355 $^{\circ}$ C tip temperature (max) 1.0mm tip diameter (max)
- Limit soldering time to 4~5 sec.



Reflow times: 3 times max.

Fig.1

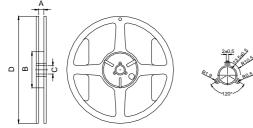


Iron Soldering times: 1 times max.

Fig.2

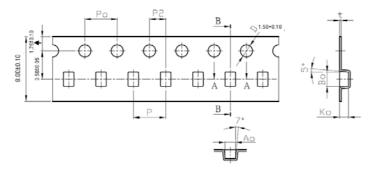
### 8. Packaging Information

#### 8-1. Reel Dimension



Туре	Type A(mm)		C(mm)	D(mm)	
7"x8mm	8.4±0.5	60±2	13.5±0.5	178±2	

#### 8-2.1 Tape Dimension / 8mm(black anti-static electricity carrier tape)

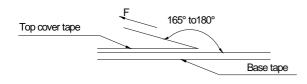


Series	P(mm)	Po(mm)	P2(mm)	Bo(mm)	Ao(mm)	Ko(mm)	t(mm)
SWI0603	4.00±0.10	4.00±0.10	2.00±0.05	1.88±0.05	1.30±0.05	1.10±0.05	0.20±0.02

#### 8-3. Packaging Quantity

Chip size	0603
Reel	3000
Reel Size	7"x8mm

#### 8-4. Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp.	oom Temp. Room Humidity		Tearing Speed	
(°C) (%)		(hPa)	mm/min	
5~35 45~85		860~1060	300	

#### **Application Notice**

• Storage Conditions(component level)

To maintain the solderability of terminal electrodes:

- 1. TAI-TECH products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- 3. Recommended products should be used within 12 months form the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
  - 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
  - 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
  - 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.



## **Test Report**

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(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

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以下測試樣品係由申請廠商所提供及確認 (The following sample(s) was/were submitted and identified by/on behalf of the applicant as):

樣品名稱(Sample Description)

CERAMIC SERIES

樣品型號(Style/Item No.)

SWI · SWC\_I SERIES

收件日期(Sample Receiving Date)

2018/03/22

測試期間(Testing Period)

2018/03/22 TO 2018/03/29

測試結果(Test Results) :

請參閱下一頁 (Please refer to following pages).



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#### 測試結果(Test Results)

測試部位(PART NAME)No.1

: 整體混測 (MIXED ALL PARTS)

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result) No.1
鎬 / Cadmium (Cd)	mg/kg	参考IEC 62321-5 (2013),以感應耦合 電漿原子發射光譜儀檢測. / With	2	n. d.
鉛 / Lead (Pb)	mg/kg	reference to IEC 62321-5 (2013) and performed by ICP-AES.	2	n. d.
汞 / Mercury (Hg)	mg/kg	參考IEC 62321-4 (2013),以感應耦合 電漿原子發射光譜儀檢測. / With reference to IEC 62321-4 (2013) and performed by ICP-AES.	2	n. d.
六價络 / Hexavalent Chromium Cr(VI)	mg/kg	参考IEC 62321-7-2 (2017),以UV-VIS 檢測. / With reference to IEC 62321-7-2 (2017) and performed by UV-VIS.	8	n. d.
多溴聯苯總和 / Sum of PBBs	mg/kg		_	n. d.
一溴聯苯 / Monobromobiphenyl	mg/kg		5	n. d.
二溴聯苯 / Dibromobiphenyl	mg/kg		5	n. d.
三溴聯苯 / Tribromobiphenyl	mg/kg	l	5	n. d.
四溴聯苯 / Tetrabromobiphenyl	mg/kg	參考IEC 62321-6 (2015),以氣相層析	5	n. d.
五溴聯苯 / Pentabromobiphenyl	mg/kg	/質譜儀檢測. / With reference to	5	n. d.
六溴聯苯 / Hexabromobiphenyl	mg/kg	IEC 62321-6 (2015) and performed by GC/MS.	5	n. d.
七溴聯苯 / Heptabromobiphenyl	mg/kg	by 607 mg.	5	n. d.
八溴聯苯 / Octabromobiphenyl	mg/kg	]	5	n. d.
九溴聯苯 / Nonabromobiphenyl	mg/kg	]	5	n. d.
十溴聯苯 / Decabromobiphenyl	mg/kg	<u> </u>	5	n. d.

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測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result)
				No. 1
多溴聯苯醚總和 / Sum of PBDEs	mg/kg		_	n. d.
一溴聯苯醚 / Monobromodiphenyl ether	mg/kg		5	n. d.
二溴聯苯醚 / Dibromodiphenyl ether	mg/kg		5	n. d.
三溴聯苯醚 / Tribromodiphenyl ether	mg/kg	参考IEC 62321-6 (2015),以氣相層析 /質譜儀檢測. / With reference to IEC 62321-6 (2015) and performed by GC/MS.	5	n. d.
四溴聯苯醚 / Tetrabromodiphenyl ether	mg/kg		5	n. d.
五溴聯苯醚 / Pentabromodiphenyl ether	mg/kg		5	n. d.
六溴聯苯醚 / Hexabromodiphenyl ether	mg/kg		5	n. d.
七溴聯苯醚 / Heptabromodiphenyl ether	mg/kg		5	n. d.
へ溴聯苯醚 / Octabromodiphenyl ether	mg/kg		5	n. d.
九溴聯苯醚 / Nonabromodiphenyl ether	mg/kg		5	n. d.
十溴聯苯醚 / Decabromodiphenyl ether	mg/kg		5	n. d.
鹵素 / Halogen				
鹵素(氟)/ Halogen-Fluorine (F) (CAS No.: 14762-94-8)	mg/kg	参考BS EN 14582 (2016),以離子層析 儀分析. / With reference to BS EN 14582 (2016). Analysis was performed by IC.	50	n. d.
鹵素(氣)/ Halogen-Chlorine (C1) (CAS No.: 22537-15-1)	mg/kg		50	n. d.
鹵素(溴)/ Halogen-Bromine (Br) (CAS No.: 10097-32-2)	mg/kg		50	n. d.
鹵素(碘)/ Halogen-Iodine(I)(CAS No.: 14362-44-8)	mg/kg		50	n. d.
鄰苯二甲酸丁苯甲酯 / BBP (Butyl Benzyl phthalate) (CAS No.: 85-68-7)	mg/kg	参考IEC 62321-8 (2017),以氣相層析 儀/質譜儀檢測. / With reference to	50	n. d.
鄰苯二甲酸二丁酯 / DBP (Dibutyl phthalate) (CAS No.: 84-74-2)	mg/kg	IEC 62321-8 (2017). Analysis was performed by GC/MS.	50	n. d.

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測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result) No.1
鄰苯二甲酸二 (2-乙基己基)酯 / DEHP (Di- (2-ethylhexyl) phthalate) (CAS No.: 117-81-7)	mg/kg	參考IEC 62321-8 (2017),以氣相層析 儀/質譜儀檢測. / With reference to IEC 62321-8 (2017). Analysis was performed by GC/MS.	50	n. d.
鄰苯二甲酸二異丁酯 / DIBP (Di- isobutyl phthalate) (CAS No.: 84-69- 5)	mg/kg		50	n. d.
鄰苯二甲酸二異癸酯 / DIDP (Di- isodecyl phthalate) (CAS No.: 26761- 40-0; 68515-49-1)	mg/kg		50	n. d.
鄰苯二甲酸二異壬酯 / DINP (Di- isononyl phthalate) (CAS No.: 28553- 12-0; 68515-48-0)	mg/kg		50	n. d.
鄰苯二甲酸二正辛酯 / DNOP (Di-n-octyl phthalate) (CAS No.: 117-84-0)	mg/kg		50	n. d.
鄰苯二甲酸二正己酯 / DNHP (Di-n-hexyl phthalate) (CAS No.: 84-75-3)	mg/kg		50	n. d.
鄰苯二甲酸二戊酯 / DNPP (Di-n-pentyl phthalate) (CAS No.: 131-18-0)	mg/kg		50	n. d.
六溴環十二烷及所有主要被辨別出的異構物 / Hexabromocyclododecane (HBCDD) and all major diastereoisomers identified ( $\alpha$ - HBCDD, $\beta$ - HBCDD, $\gamma$ - HBCDD) (CAS No.: 25637-99-4 and 3194-55-6 (134237-51-7, 134237-50-6, 134237-52-8))	mg/kg	参考IEC 62321 (2008),以氣相層析/ 質譜儀檢測. / With reference to IEC 62321 (2008). Analysis was performed by GC/MS.	5	n. d.

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#### 備註(Note):

- 1. mg/kg = ppm ; 0.1wt% = 1000ppm
- 2. n.d. = Not Detected (未檢出)
- 3. MDL = Method Detection Limit (方法偵測極限值)
- 4. "-" = Not Regulated (無規格值)
- 5. 樣品的測試是基於申請人要求混合測試,報告中的混合測試結果不代表其中個別單一材質的含量. (The samples was/were analyzed on behalf of the applicant as mixing sample in one testing. The above results was/were only given as the informality value.)

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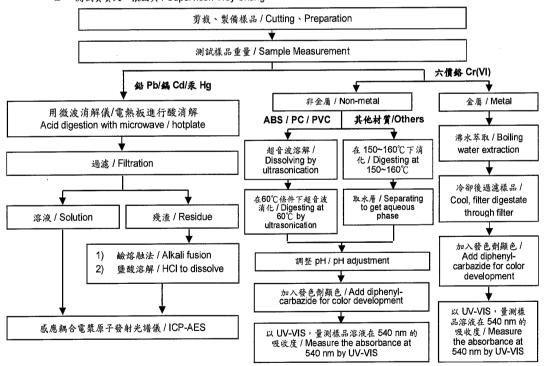
#### 重金屬流程圖 / Analytical flow chart of Heavy Metal

根據以下的流程圖之條件,樣品已完全溶解。(六價鉻測試方法除外)

These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr<sup>6+</sup> test method excluded)

測試人員:王志瑋 / Technician: JR Wang

測試負責人:張啟興 / Supervisor: Troy Chang



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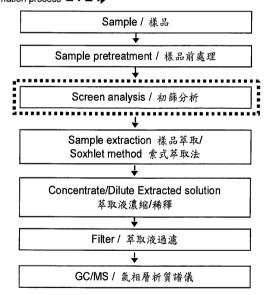
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### 多溴聯苯/多溴聯苯醚分析流程圖 / Analytical flow chart - PBB/PBDE

測試人員:涂雅苓 / Technician: Yaling Tu

測試負責人:張啟興 / Supervisor: Troy Chang

初次測試程序 / First testing process \_ 選擇性篩檢程序 / Optional screen process •••• 確認程序 / Confirmation process \_ - - - - ▶



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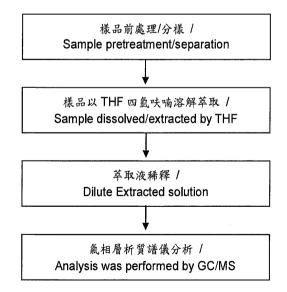
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#### 可塑劑分析流程圖 / Analytical flow chart - Phthalate

測試人員:徐毓明 / Technician: Andy Hsu

測試負責人:張啟興 / Supervisor: Troy Chang

【測試方法/Test method: IEC 62321-8】



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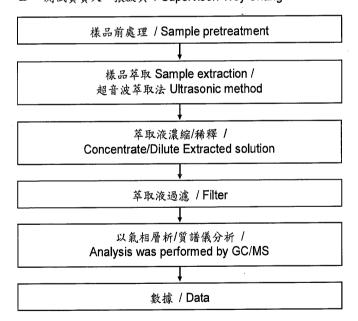
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### 六溴環十二烷分析流程圖 / Analytical flow chart - HBCDD

- 測試人員:涂雅苓 / Technician: Yaling Tu
- 測試負責人:張啟興 / Supervisor: Troy Chang



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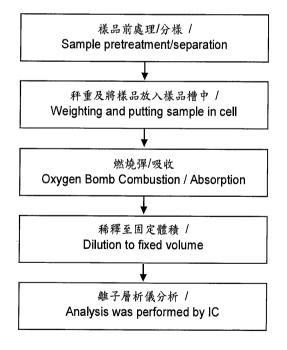
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#### <u> 由素分析流程圖 / Analytical flow chart - Halogen</u>

測試人員:陳恩臻 / Technician: Rita Chen

測試負責人:張啟興 / Supervisor: Troy Chang



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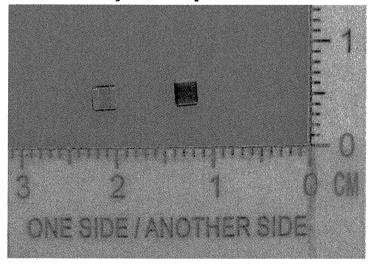
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> \* 照片中如有箭頭標示,則表示為實際檢測之樣品/部位. \* (The tested sample / part is marked by an arrow if it's shown on the photo.)

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